



Serial No. 10/689,936
IIZ.003D2C
Amendment dated May 23, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

Serial No.: 10/689,936

Examiner: F. Toledo

Filed: October 22, 2003

Confirm No.: 4027

For: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

AMENDMENT

U.S. Patent and Trademark Office
Customer Window, **Mail Stop Amendment**
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Date: May 23, 2005

Sir:

In response to the Office Action dated December 23, 2004, the period for response having been extended two (2) months to May 23, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.